

Electronic Patent Application Fee Transmittal

Application Number:	10593137
Filing Date:	18-Sep-2006
Title of Invention:	Resin Composition and Semiconductor Device Produced By Using the Same
First Named Inventor/Applicant Name:	Hikaru Okubo
Filer:	Robert G. Weilacher/Bess Murray
Attorney Docket Number:	033036.110

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 3 months with \$0 paid	1253	1	1110	1110

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				1110